



Product / Process Change Notice

No.: Z200-PCN-DM201608-01-A

Date: 08/24/2016

Change Title : W25Q32JV "J-Series" (58nm) to replace W25Q32FV "F-Series" (58nm) 32Mb SpiFlash® Memories

Change Classification: Major Minor

Change item : Design Raw Material Wafer FAB Assembly Packing Testing Others

Affected Product(s) :

W25Q32FVSSIF ,W25Q32FVSSIG ,W25Q32FVSSIP ,W25Q32FVSSIQ ,W25Q32FVSFIG ,W25Q32FVSFIQ ,
W25Q32FVDAIG ,W25Q32FVDAIQ ,W25Q32FVZPIG ,W25Q32FVZPIQ ,W25Q32FVTBIG ,W25Q32FVTCIG

Description of Change(s)

The W25Q32JV 32Mb SpiFlash® Memories use Winbond's 58nm Flash technology. It is function-compatible with W25Q32FV 58nm devices offering improved performance, features and availability. (Please refer attachment I)

Reason for Change(s) :

Improve features and Command backward compatible with W25Q32FV.

Impact of Change(s) : (positive & negative)

Form : No Change

Fit : No Change

Function : No Concern (Please refer to attachment I)

Reliability : No Concern (Please refer to attachment II)

Hazardous Substances: No Concern (Please refer to attachment III)

Qualification Plan/ Results :

Based on Winbond W25Q32JV Serial Flash Reliability report, the new product meets our criteria and no quality concern. (refer to Attachment II in details)

Implementation Plan :

Please refer to Attachment IV for details.

Date Code: ____ onward Lot No: ____ onward Proposed first ship date: Please refer to Attachment IV

Originator: (QA)

Hyhuang

**Approval: (QA
Dept. Manager)**

YH Chang

**Approval: (QRA
Director)**

Genon
Chen

**Contact for Questions
& Concerns**

Name: Betty Huang TEL:886-3-5678168 (ext.86549) FAX: 886-3-5796124
Address : # 539, Sec. 2, Wenxing Rd., Jhubei City, Hsinchu County 302, Taiwan
E-mail: Hyhuang8@winbond.com



Customer Comments:

Note: Please sign this notice, and return to Winbond contact within 30 days. If no response is received within 30 days, this Change Request will be assumed to meet your approval.

Approval Disapproval Conditional Approval : _____.

Comment:

Date: _____

Dept. name: _____

Person in charge: _____



Winbond Electronics Corporation

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Product Obsolescence Notice

W25Q32JV SpiFlash Memories

Notification Date: Aug, 11, 2016

Dear Valued Customer,

This letter is to notify you of Winbond’s intention to terminate production of the W25Q32FV SpiFlash memory, and replace it with the W25Q32JV. Replacement part numbers are listed below:

Winbond Current PN (58nm F-Series)	Winbond Primary Replacement PN (58nm J-Series)
W25Q32FVSSIG W25Q32FVSSIQ W25Q32FVSSIF W25Q32JVSSIP	W25Q32JVSSIQ
W25Q32FVSFIG W25Q32FVSFIQ	W25Q32JVSFIQ
W25Q32FVDAIG W25Q32FVDAIQ	W25Q32JVDAIQ
W25Q32FVZPIG W25Q32FVZPIQ	W25Q32JVZPIQ
W25Q32FVTBIG	W25Q32JVTBIQ
W25Q32FVTCIG	W25Q32JVTCIQ

The W25Q32JV device features:

Features

- a) Command backward compatible with W25Q32FV (same Superset Instruction Set)
- b) Clock operation up to 133MHz
- c) Lower power consumption
- d) SPI with Single / Dual / Quad
- e) Flexible architecture with 4KB sectors

Please refer to the table below for your particular product last time order date and Winbond last shipment date and use this table to determine your last time buys and subsequent request dates. Winbond Electronics reserves the right to limit last time buy quantities based on capacity and material availability. Please notify Winbond as soon as possible if there are any concerns with these this schedule.

Part Number	Notification Date	Last Order Date	Last Ship Date	Part Number	Reliability Report	Mass Production
W25Q32FV	Jul./21/ 2016	Jan./21/ 2017	Jul./21/ 2017	W25Q32JV	Aug./15/ 2016	Mar./24/ 2016



Eddy Hung

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Assistant Vice President of Flash Marketing